Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)

Contact Info:

ti.com/support
Distribute - RoHS and IEC 62474 DB Form/Declaration Type:

06/02/2022 Created on:

### Details for "LMP7732MAX/NOPB"

### **Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
LMP7732MAX/NOPB	SN	Level-1-260C-UNLIM	Texas Instruments Electronics	D   8	4.9 x 3.9 x 1.75	184.1

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

## **Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

### Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.075815	100	1000000	0.041185	412
Sub-Total			0.075815	100	1000000	0.041185	412
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.184694	74.999898	749999	0.100331	1003
Thermoplastics	Ероху	85954-11-6	0.061565	25.000102	250001	0.033444	334
Sub-Total			0.246259	100	1000000	0.133775	1338
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	120.322305	97.585	975850	65.362344	653623
Copper and Its Alloys	Iron	7439-89-6	2.8359	2.3	23000	1.540538	15405
Copper and Its Alloys	Phosphorus	7723-14-0	0.018495	0.015	150	0.010047	100
Zinc and Its Alloys	Zinc	7440-66-6	0.1233	0.1	1000	0.06698	670
Sub-Total			123.3	100	1000000	66.979908	669799
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	1	100	1000000	0.543227	5432
Sub-Total			1	100	1000000	0.543227	5432
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	51.736648	89	890000	28.104752	281048
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	1.743932	3	30000	0.947351	9474
Thermoplastics	Epoxy	85954-11-6	4.650485	8	80000	2.52627	25263
Sub-Total			58.131065	100	1000000	31.578373	315784
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.331914	100	1000000	0.723532	7235
Sub-Total			1.331914	100	1000000	0.723532	7235
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Total			184.085053			100	1000000

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

## Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

For an explanation of the methods used to determine material weights, See Product Content Methodology

# Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

## Important Information/Disclaimer

Tl bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. Tl may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is." For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/02/2022

ROHS: Means TI semiconductor products that are compliant with the current ROHS requirement that the maximum concentration values of the ten substances listed in ROHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

ROHS Exempt: Means TI semiconductor products that contain lead (Pb) above the ROHS Annex II threshold, but that fall within one of the specific ROHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzo088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (5b203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.